

Product Summary

BV_{DSS}	$R_{DS(ON)}$ Max	I_D Max $T_A = 25^\circ C$
60V	6m Ω @ $V_{GS} = 10V$	13.5A
	8.9m Ω @ $V_{GS} = 4.5V$	11.3A

Features and Benefits

- High Conversion Efficiency
- Low $R_{DS(ON)}$ – Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

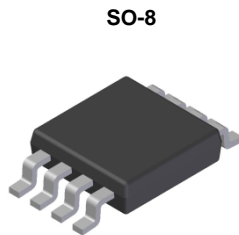
Description and Applications

This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

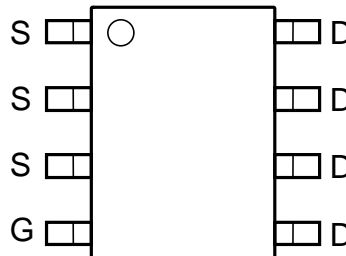
- High Frequency Switching
- Synchronous Rectification
- DC-DC Converters

Mechanical Data

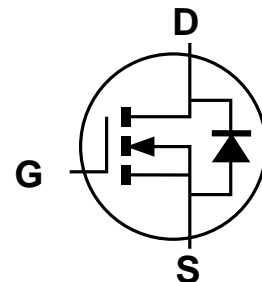
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 $\text{\textcircled{E}}$
- Weight: 0.074 grams (Approximate)



Top View



Top View
Internal Schematic



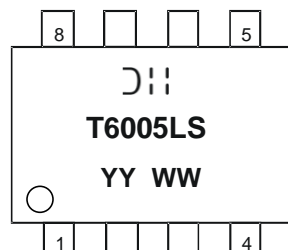
Equivalent circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMT6005LSS-13	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



-]:] = Manufacturer's Marking
 T6005LS = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 15 = 2015)
 WW = Week (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State T _A = +25°C T _A = +70°C	I _D	13.5
		I _D	10.8
	t < 10s T _A = +25°C T _A = +70°C	I _D	18.1
		I _D	14.4
Maximum Continuous Body Diode Forward Current (Note 6)	I _S	3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	80	A
Avalanche Current, L = 1mH	I _{AS}	14.8	A
Avalanche Energy, L = 1mH	E _{AS}	98	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State t < 10s	R _{θJA}	93
		R _{θJA}	53
Total Power Dissipation (Note 6)	P _D	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State t < 10s	R _{θJA}	73
		R _{θJA}	41
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}	12.7	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	—	—	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	µA	V _{DS} = 48V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1	—	3	V	V _{DS} = V _{GS} , I _D = 250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	5	6	mΩ	V _{GS} = 10V, I _D = 20A
		—	5.7	7.2		V _{GS} = 6V, I _D = 20A
		—	6.7	8.9		V _{GS} = 4.5V, I _D = 12.5A
Diode Forward Voltage	V _{SD}	—	0.9	1.2	V	V _{GS} = 0V, I _S = 20A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	2962	—	pF	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz
Output Capacitance	C _{oss}	—	965	—		
Reverse Transfer Capacitance	C _{rss}	—	60	—		
Gate Resistance	R _g	—	0.66	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 10V)	Q _g	—	47.1	—	nC	V _{DD} = 30V, I _D = 20A
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	23.1	—		
Gate-Source Charge	Q _{gs}	—	10.2	—		
Gate-Drain Charge	Q _{gd}	—	12.5	—		
Turn-On Delay Time	t _{D(ON)}	—	8.3	—	nS	V _{DD} = 30V, V _{GS} = 10V, I _D = 20A, R _g = 3.3Ω
Turn-On Rise Time	t _R	—	9.4	—		
Turn-Off Delay Time	t _{D(OFF)}	—	22	—		
Turn-Off Fall Time	t _F	—	8.9	—		
Body Diode Reverse Recovery Time	t _{RR}	—	40.4	—	nS	I _F = 20A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}	—	49.7	—	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1 inch square copper plate.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

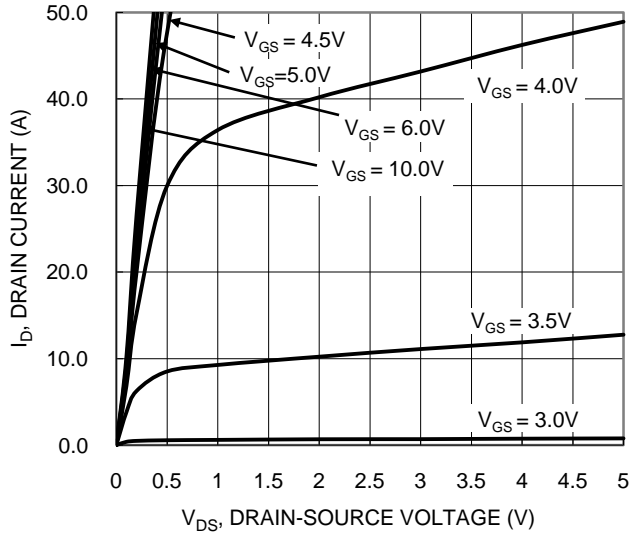


Figure 1. Typical Output Characteristic

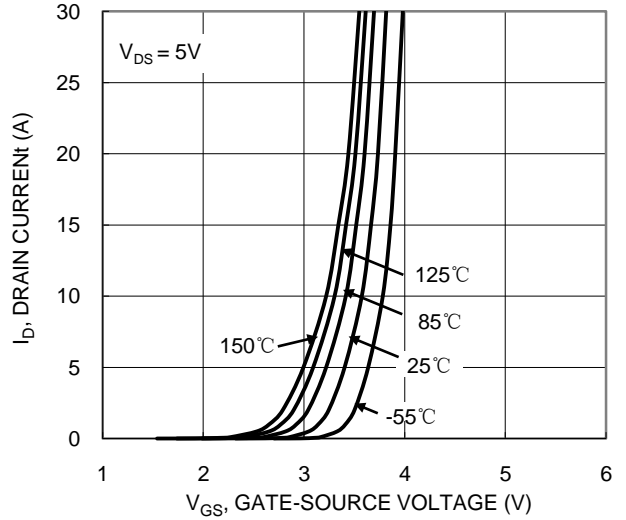


Figure 2. Typical Transfer Characteristic

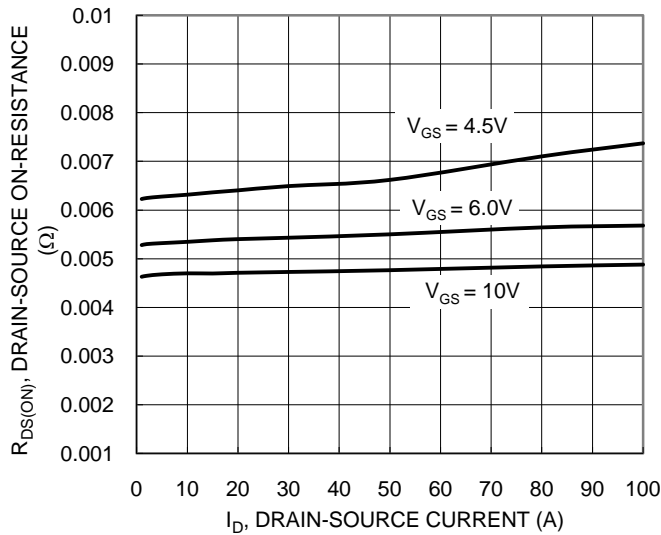


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

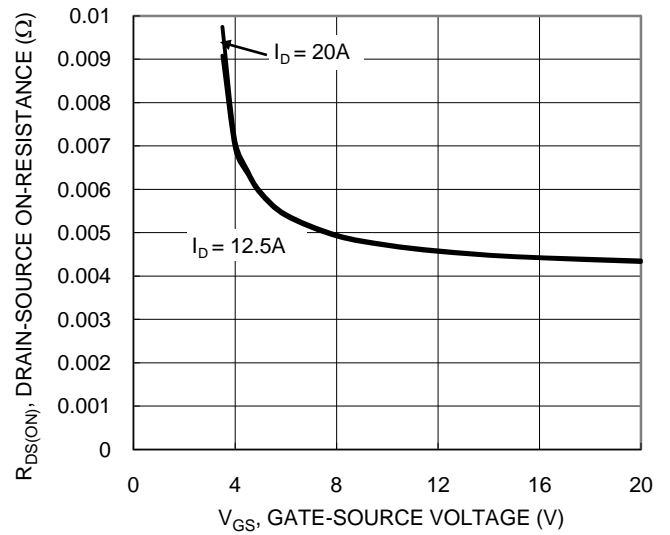


Figure 4. Typical Transfer Characteristic

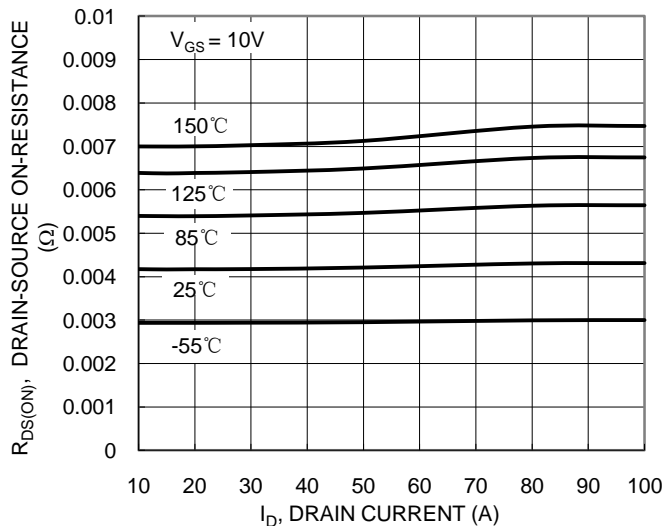


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

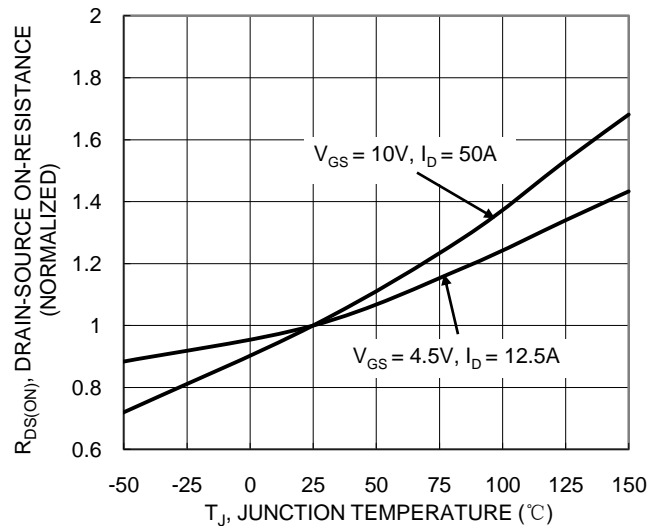


Figure 6. On-Resistance Variation with Junction Temperature

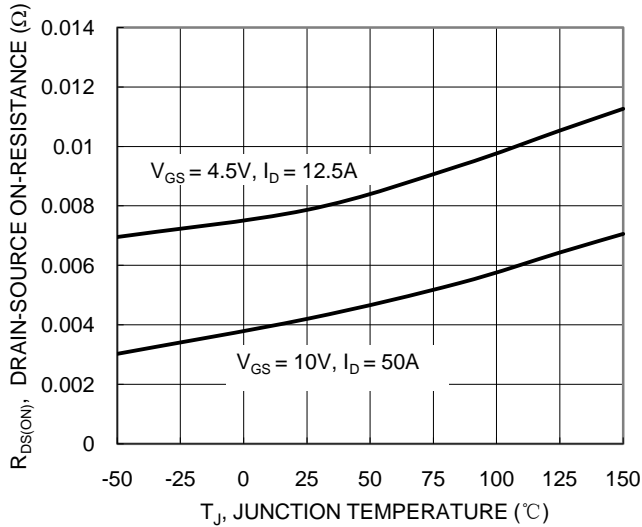


Figure 7. On-Resistance Variation with Junction Temperature

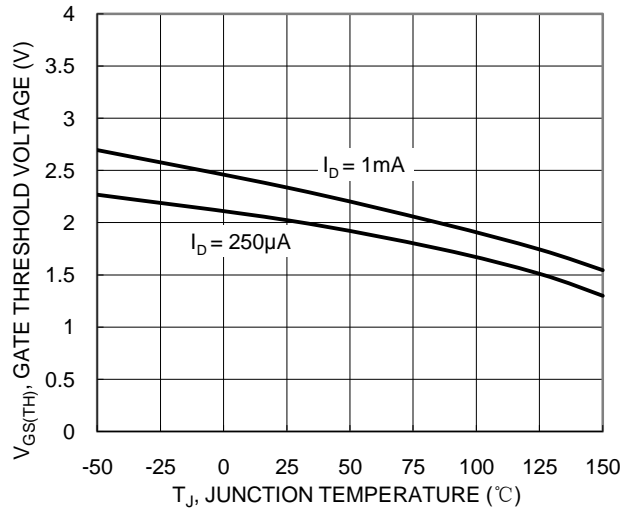


Figure 8. Gate Threshold Variation vs. Junction Temperature

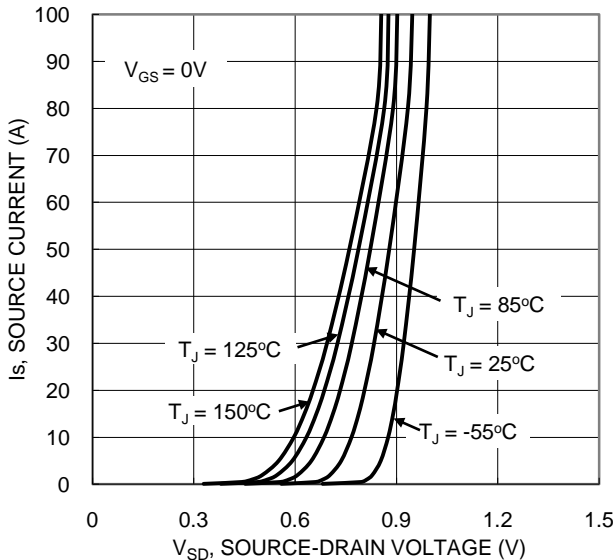


Figure 9. Diode Forward Voltage vs. Current

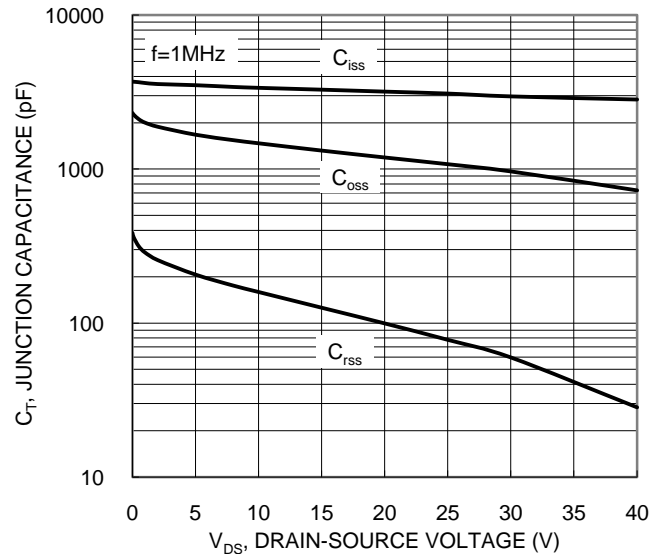


Figure 10. Typical Junction Capacitance

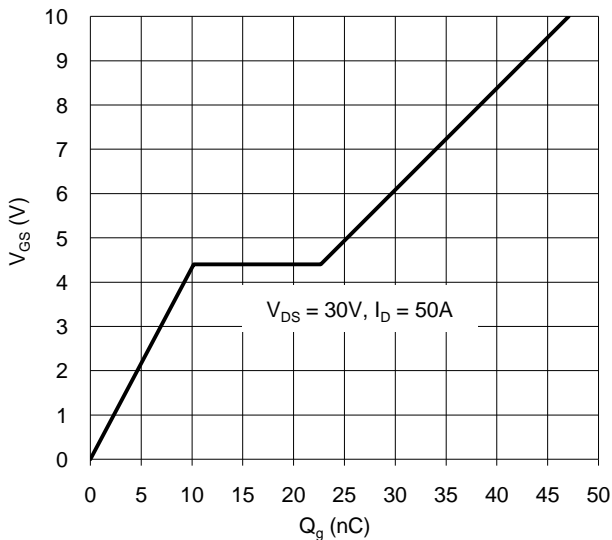


Figure 11. Gate Charge

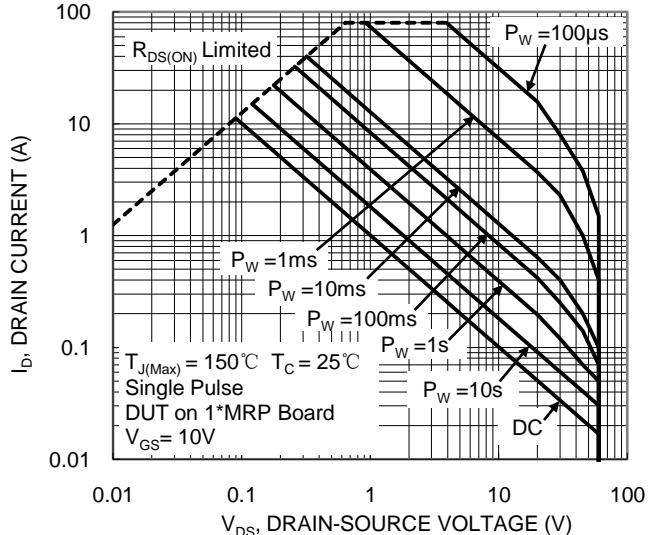


Figure 12. SOA, Safe Operation Area

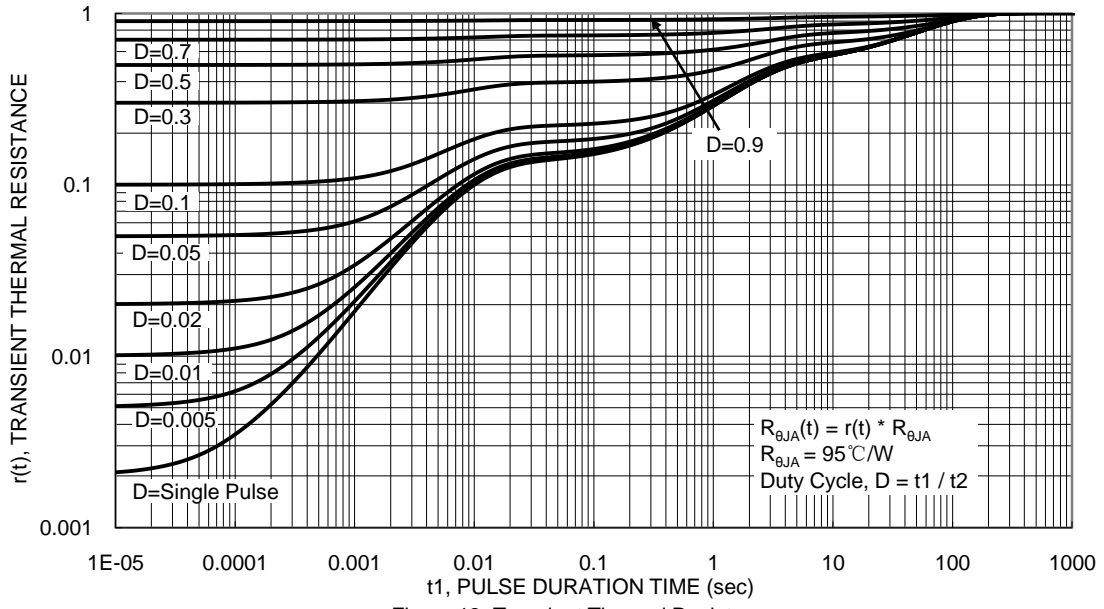
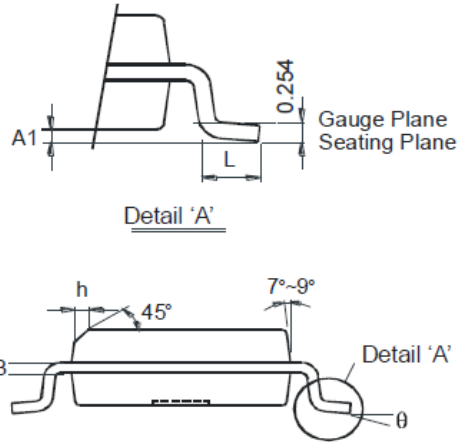
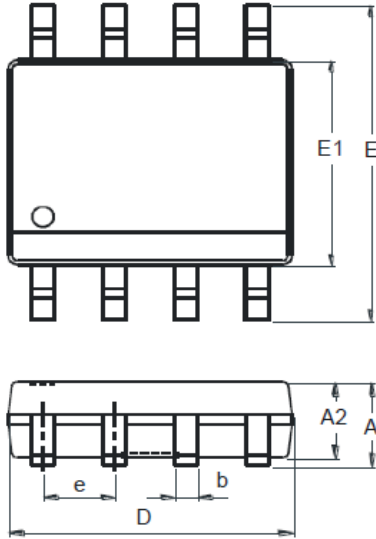


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8

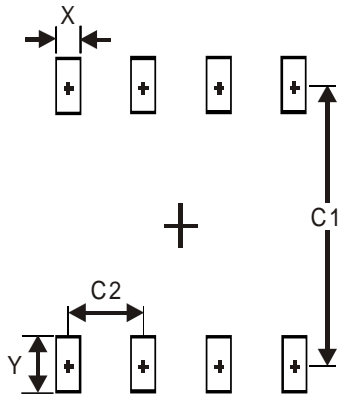


SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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